

Title (en)

METHOD AND APPARATUS FOR INTEGRATED CHEMICAL MECHANICAL POLISHING OF COPPER AND BARRIER LAYERS

Title (de)

VERFAHREN UND GERÄT ZUM INTEGRIERTEN CHEMISCH-MECHANISCHEN POLIEREN VON KUPFER- UND BARRIERESCHICHT

Title (fr)

PROCEDE ET APPAREIL DE POLISSAGE CHIMICO-MECANIQUE INTEGRE DU CUIVRE, ET COUCHES BARRIERE

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Application

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Abstract (en)

[origin: WO03079428A1] A method of polishing a plurality of layers on a surface of a semiconductor wafer includes polishing a first layer such as copper using a polishing solution on a first portion of polishing pad and polishing another layer as a barrier layer using a polishing solution on another portion of polishing pad. Different or identical solutions may be used for each layer. The different portions of polishing pad, likewise, are preferably suited to polish a corresponding wafer layer. The different portions of polishing pad may be located on the same pad or on different pads. Also claimed are two different supply lines of polishing solutions to a single polishing pad.

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